

Figure 2-1 The calculated binary phase diagram of GaN

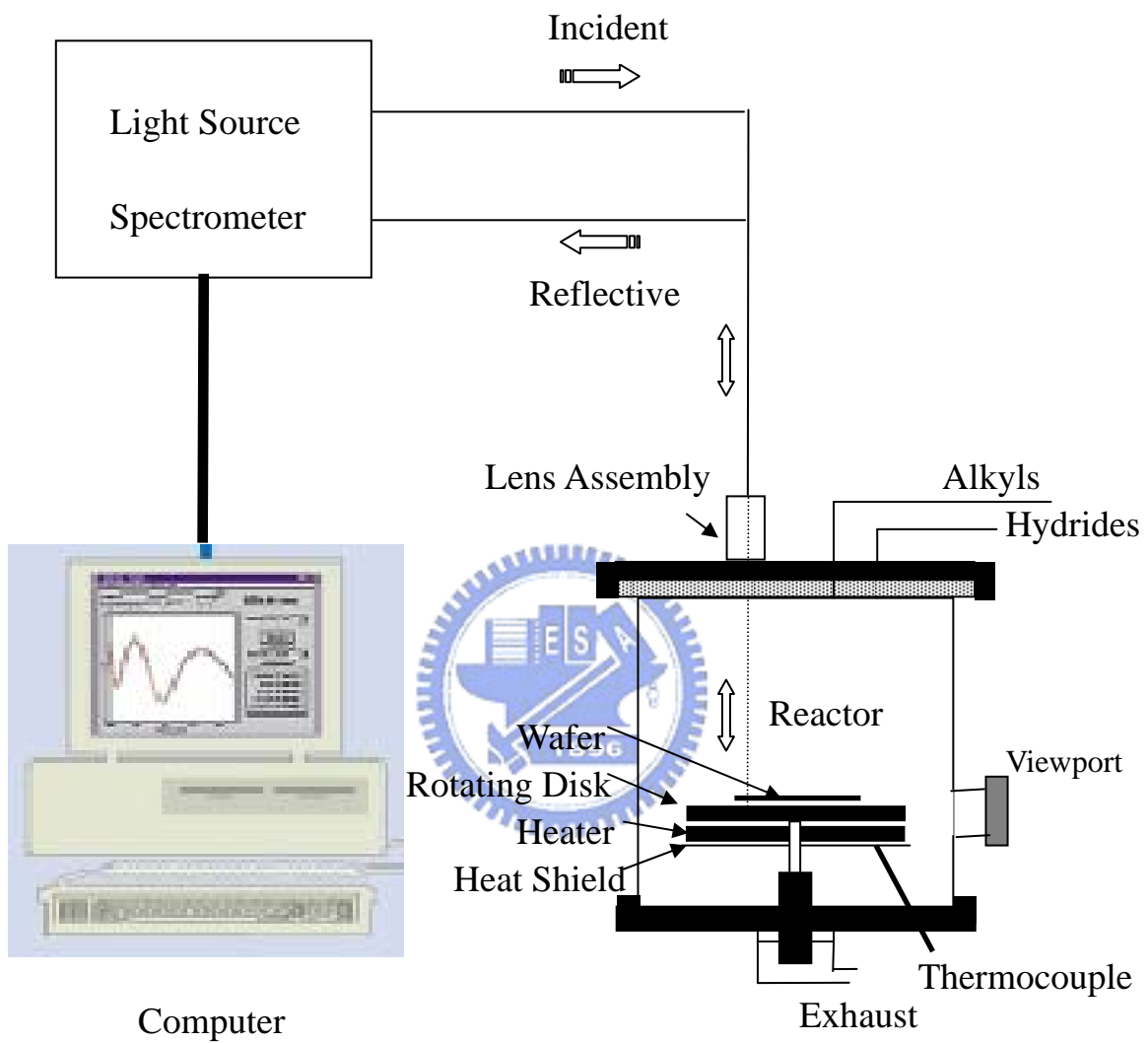
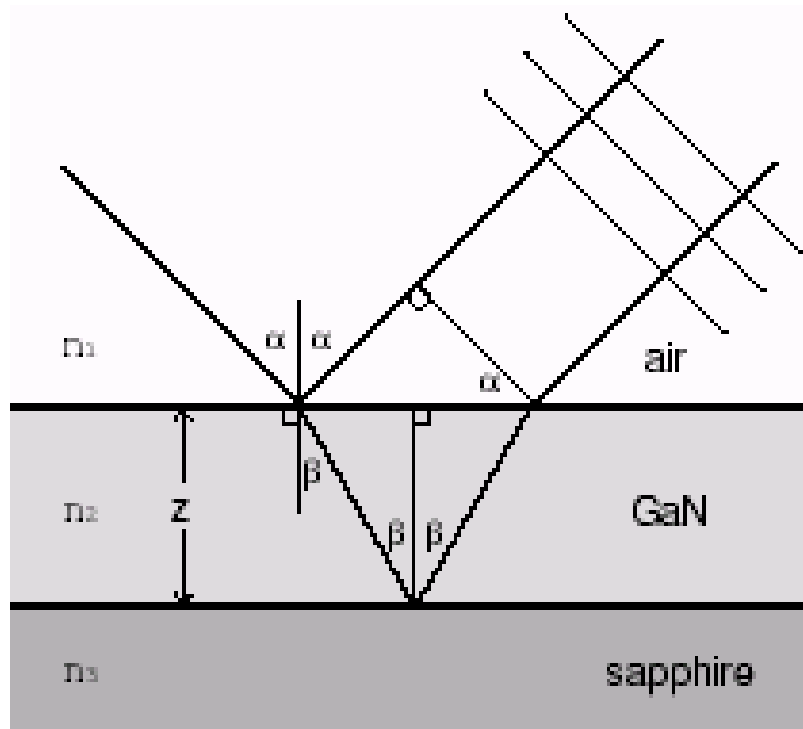
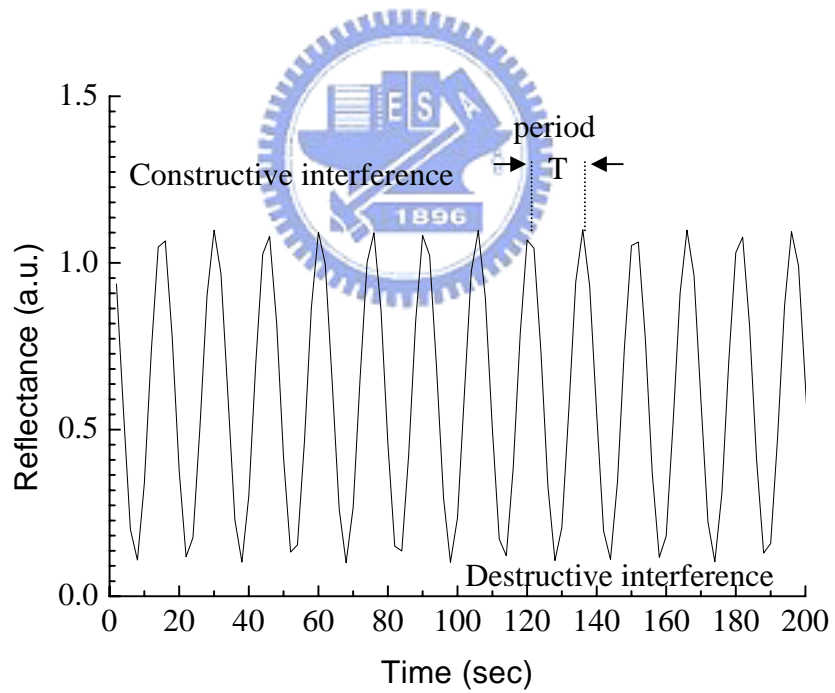


Figure 2-2. Schematic diagram of the in-situ monitoring system.



(a)



(b)

Figure 2-3. (a) A diagram of thin-film interference with dielectric materials. Coherent light illuminates the wafer surface during the film deposition and the reflected light is sampled with a photodiode. (b) The reflectance spectrum for single layer epitaxy in constant growth rate case.

(a). Pretreatment of sapphire substrate

(b). buffer GaN growth

(c). epitaxy GaN growth

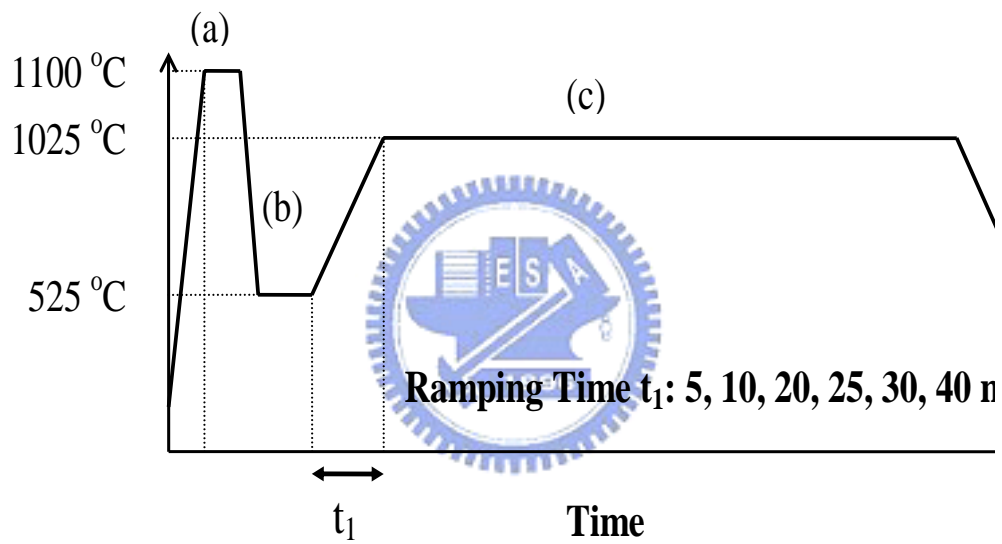


Figure 2-4 Thermal profile for the growth of GaN epitaxial layer. The ramping time  $t_1$  varied from 525 °C to 1025 °C after the grown LT-GaN buffer layer.

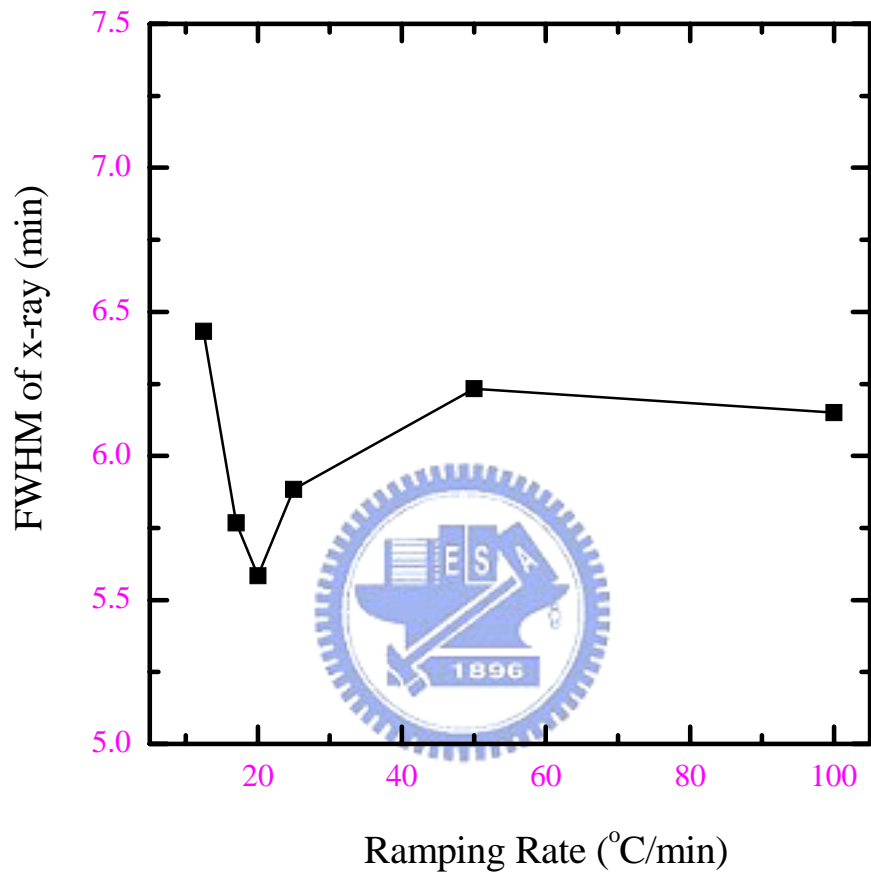


Figure 2-5. The FWHM of XRD for (0004) diffraction from the GaN epitaxial layer as a function of the temperature ramping rate between 525°C and 1025°C after grown LT-GaN buffer layer

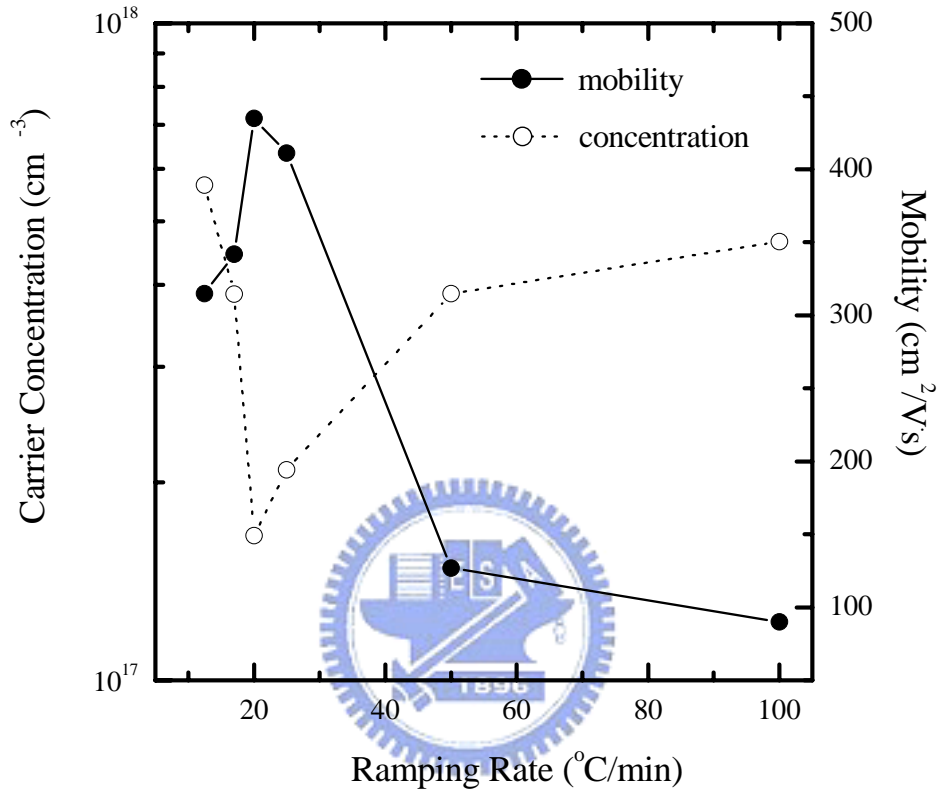


Figure 2-6. The Hall mobility and carrier concentration measured at 300K as a function of the temperature ramping rate between 525°C and 1025°C after grown LT-GaN buffer layer.

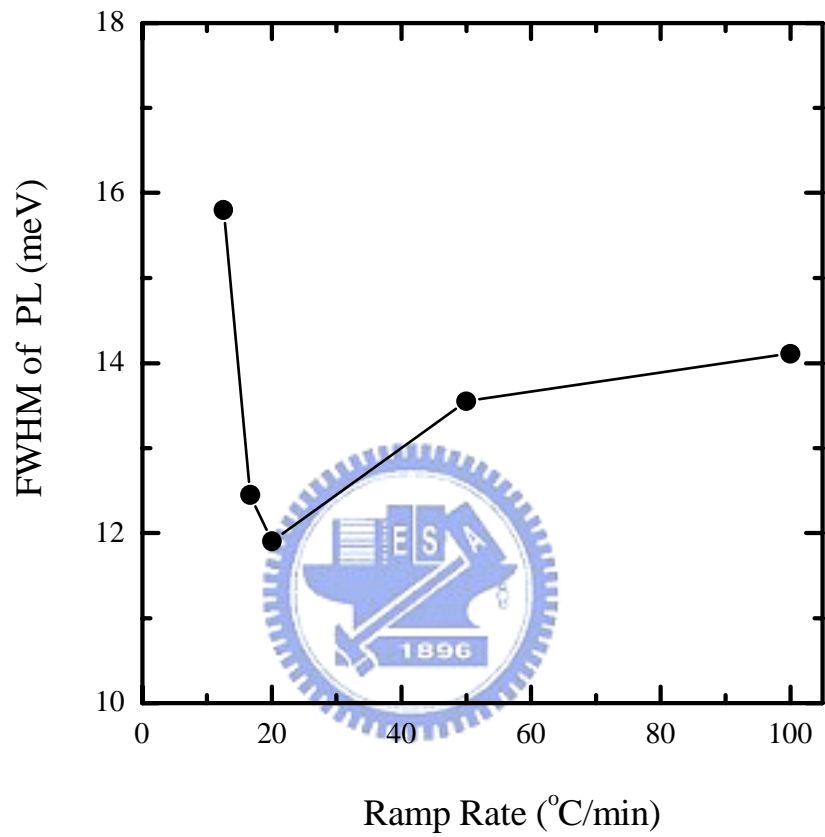


Figure 2-7. 10K photoluminescence linewidths (FWHM) for GaN epitaxial layer as a function of the temperature ramping rate between 525°C and 1025°C after grown LT-GaN buffer layer.

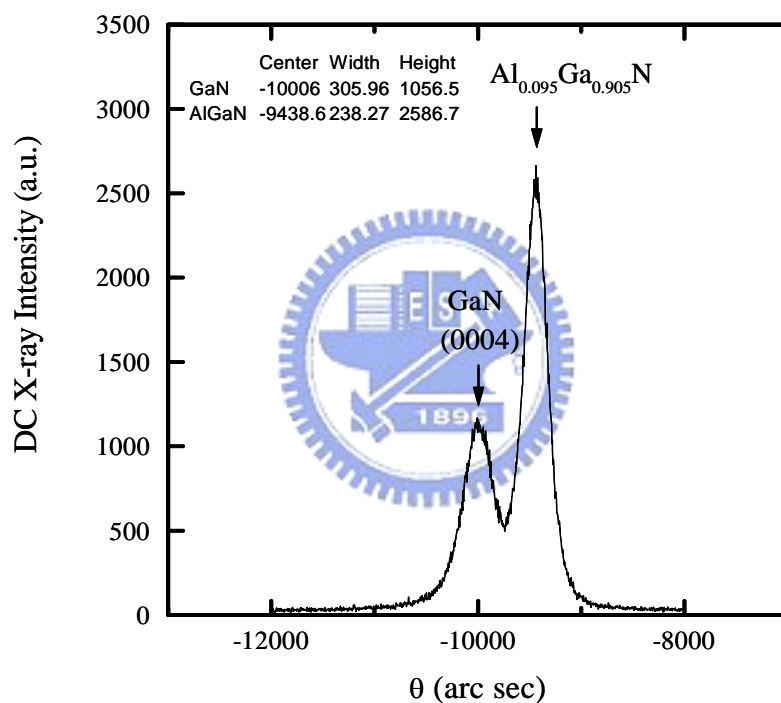
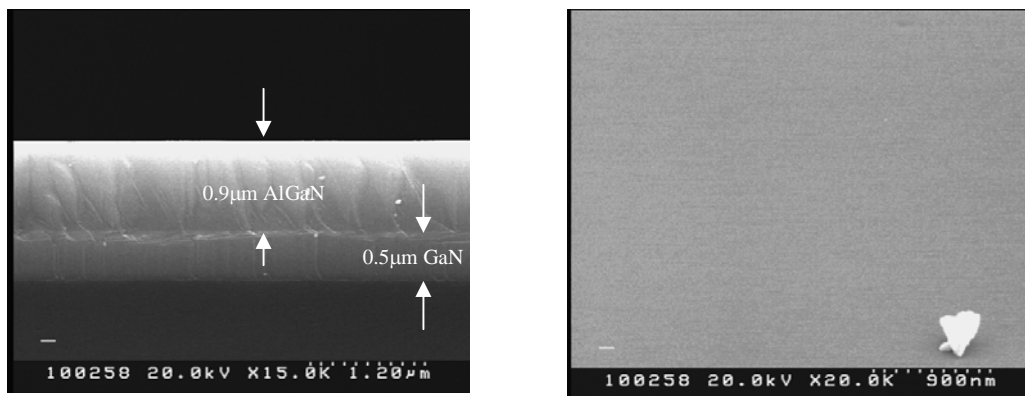


Figure 2-8. The thickness and surface morphology of AlGaIn/GaN double layers were observed from the SEM photograph. The GaN (0004) and Al<sub>x</sub>Ga<sub>1-x</sub>N (0004) peaks were showed in x-ray diffraction curve.



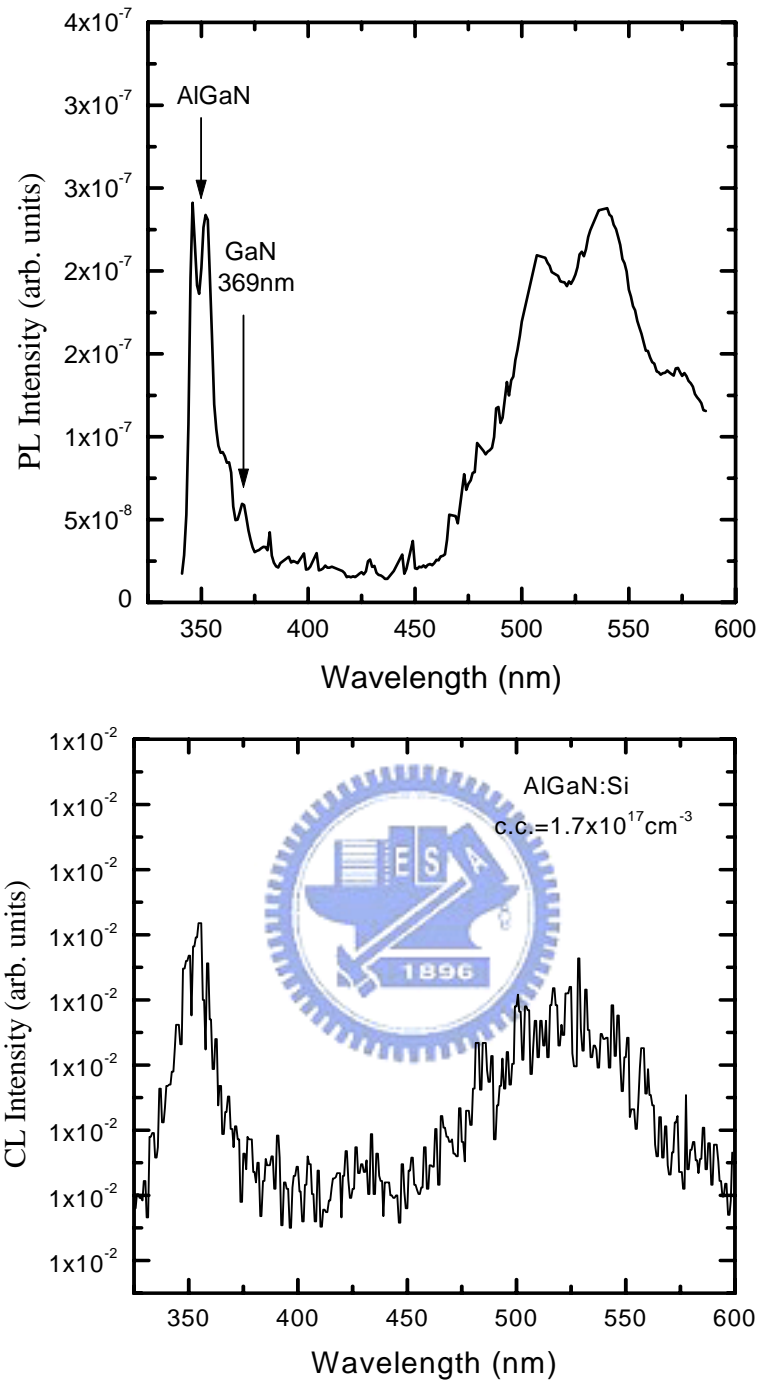


Figure 2-9. The AlGaIn peak, GaN peak and yellow peak were observed from PL and CL Spectrums at RT

Fix the V/III (N/(Al+Ga)) ratio at 10000  
Varied the Al/(Al+Ga)mole flow ratio from 0 to 1  
● Al/(Al+Ga)mole flow ratio  
cacluated by Vegard's law

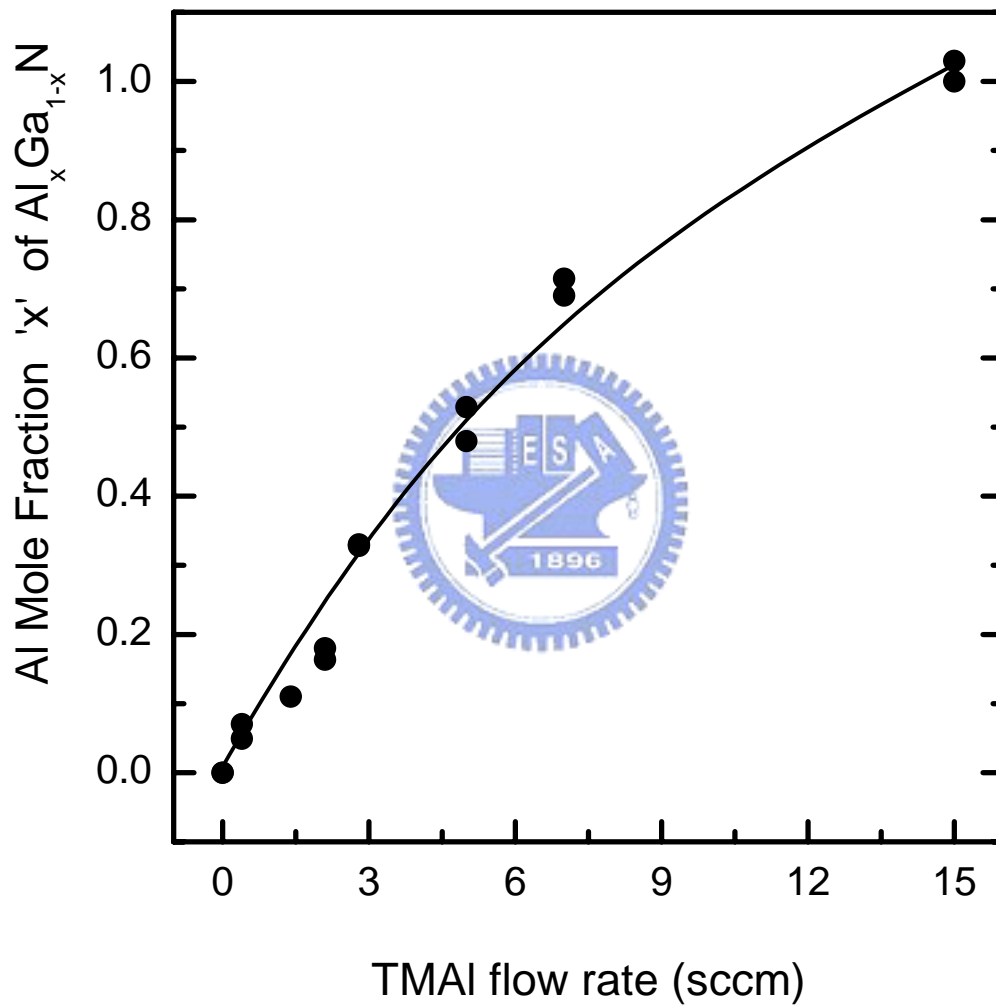


Figure 2-10. The dependence of Al mole fraction on TMAI flow rate for  $A_xGa_{1-x}N$  epitaxial growth.

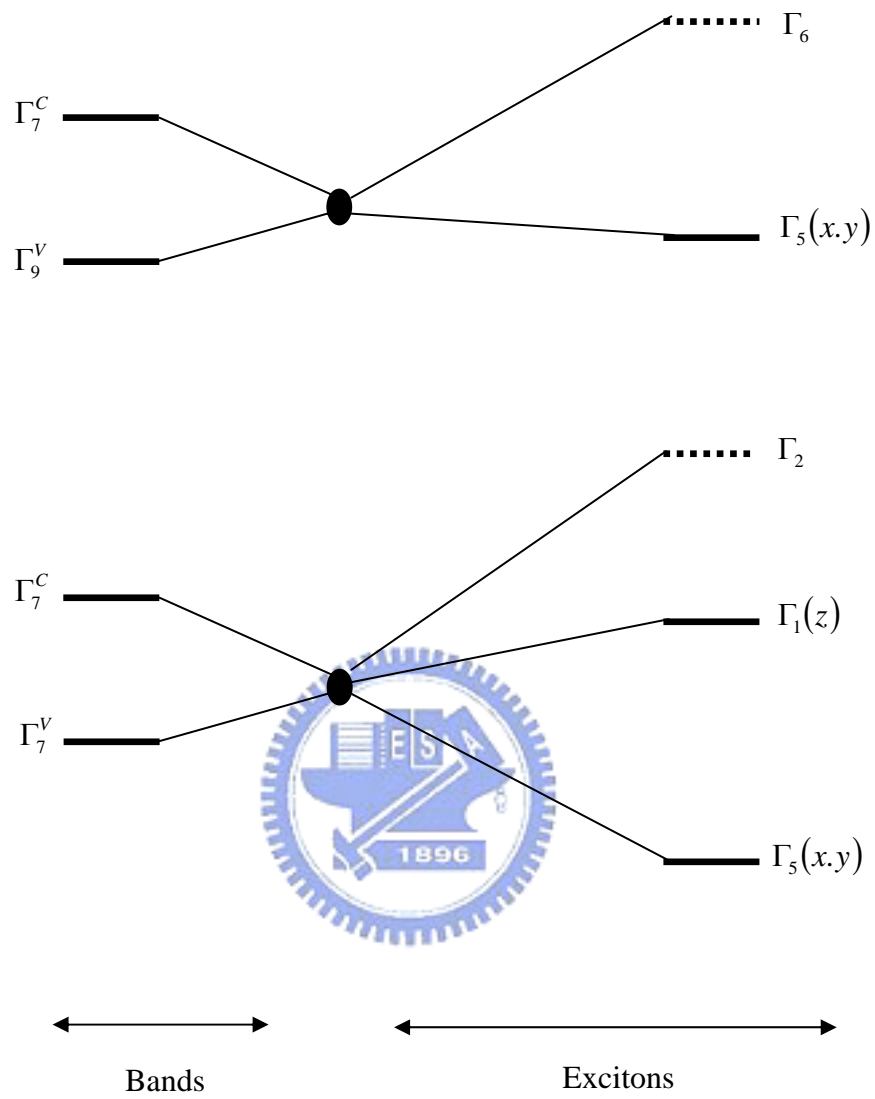


Figure 2-11. Sketch of the construction of the exciton states from the combination of conduction and valence band Bloch state for epitaxy on C-plane.

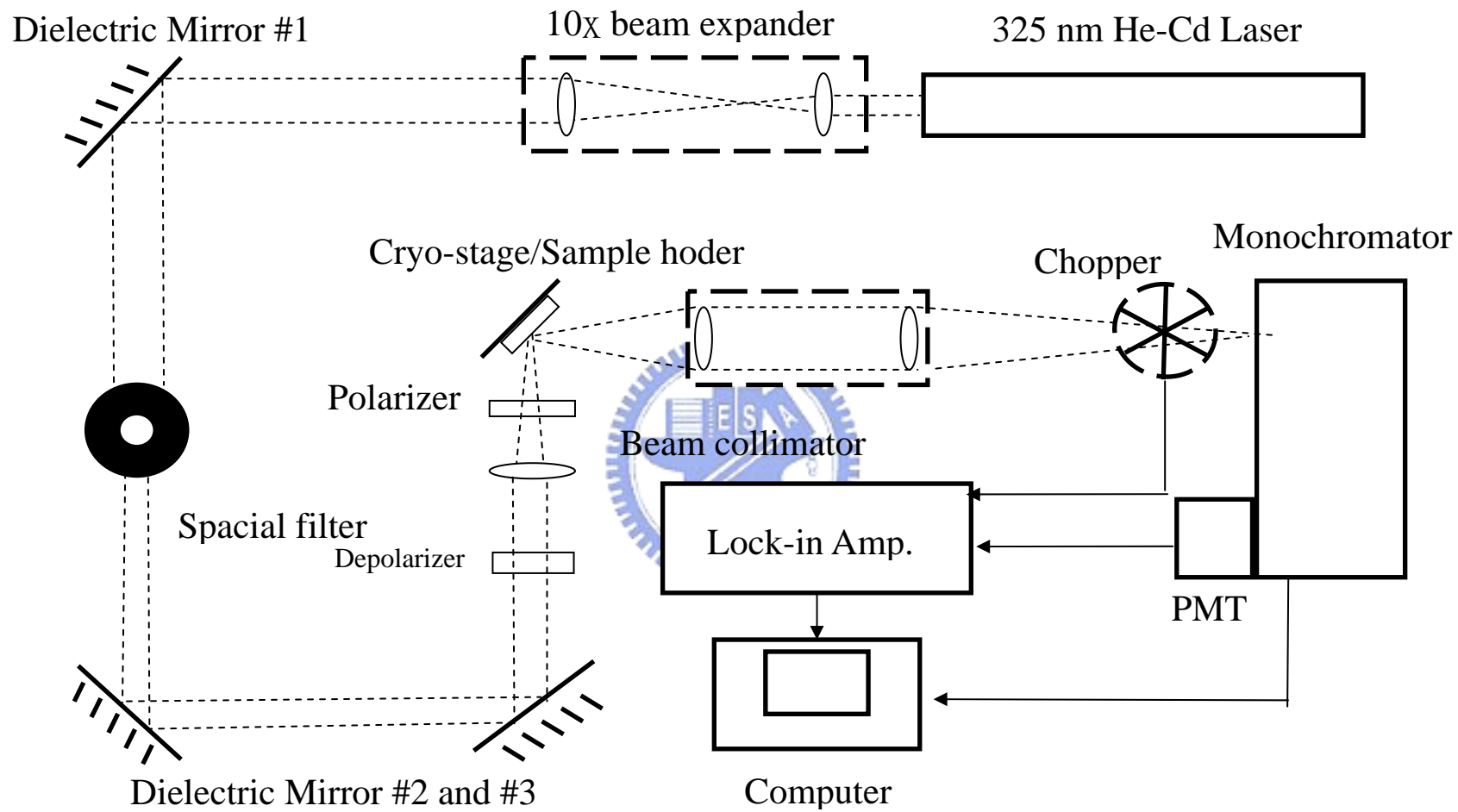


Figure 2-12. Schematic of PL measurement system.

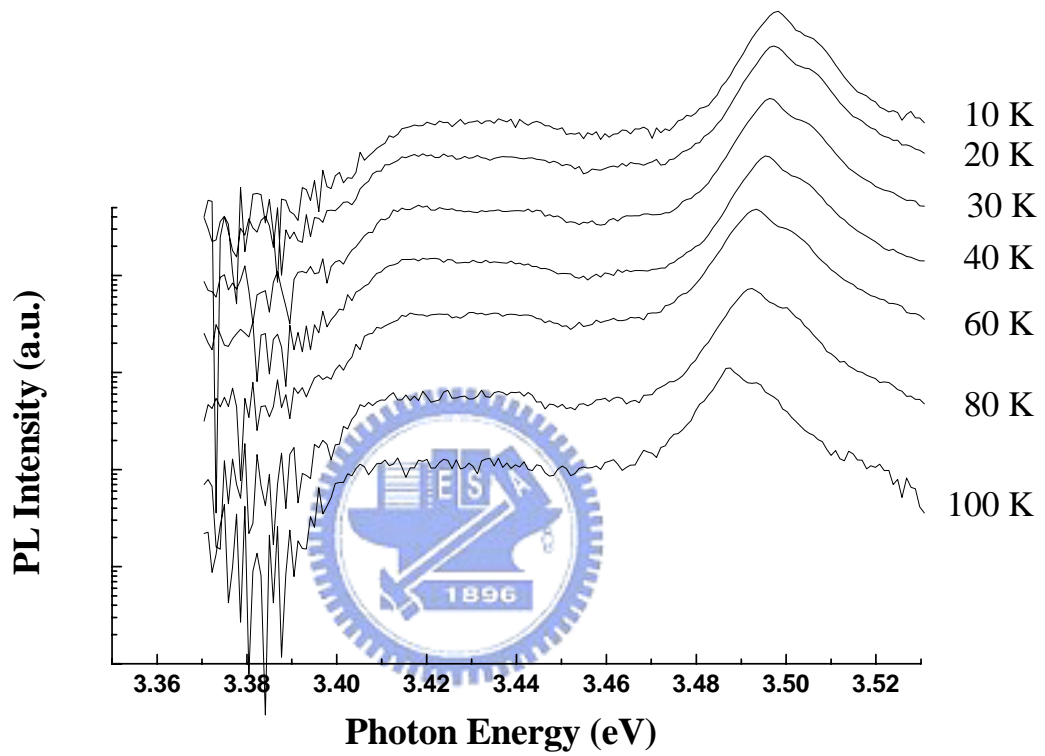


Figure 2-13. Typical PL spectra near the band edge emissions at low temperatures.

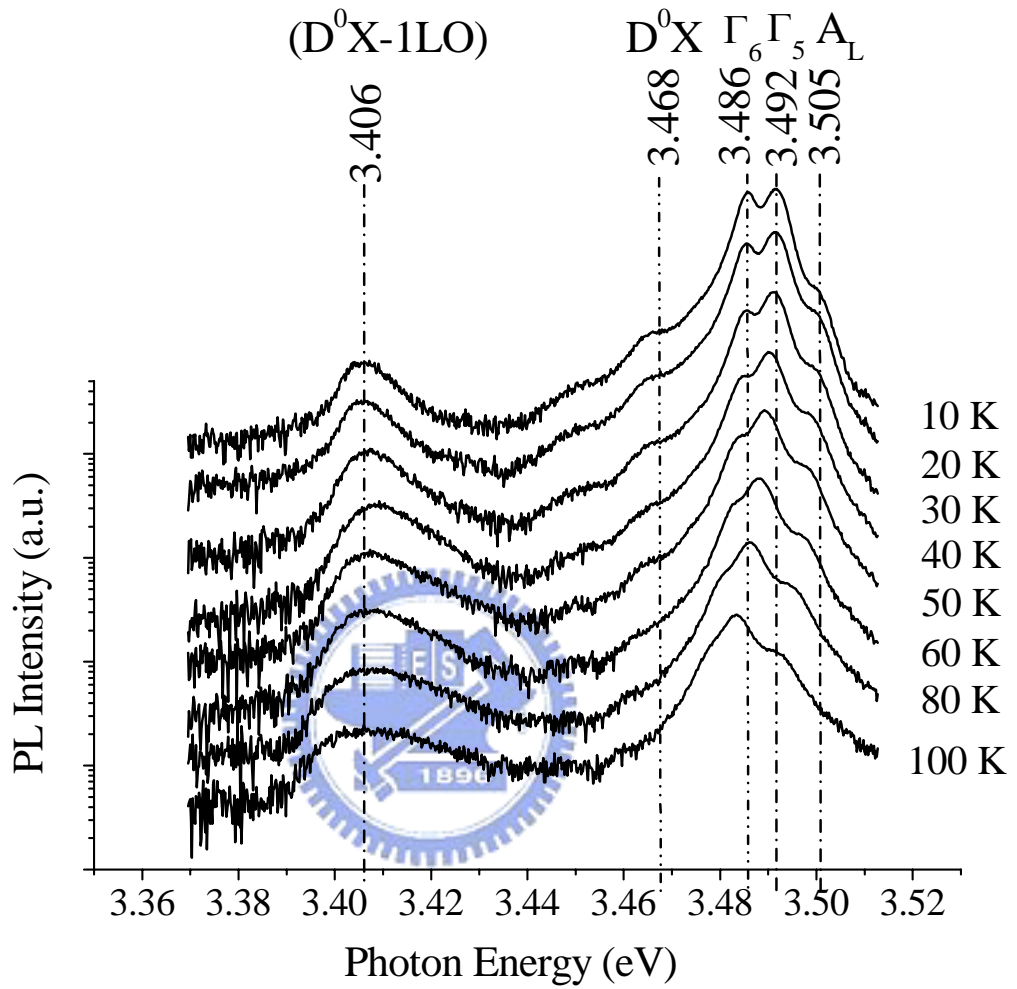


Figure 2-14. PL spectra of the high quality UID GaN at different temperature.

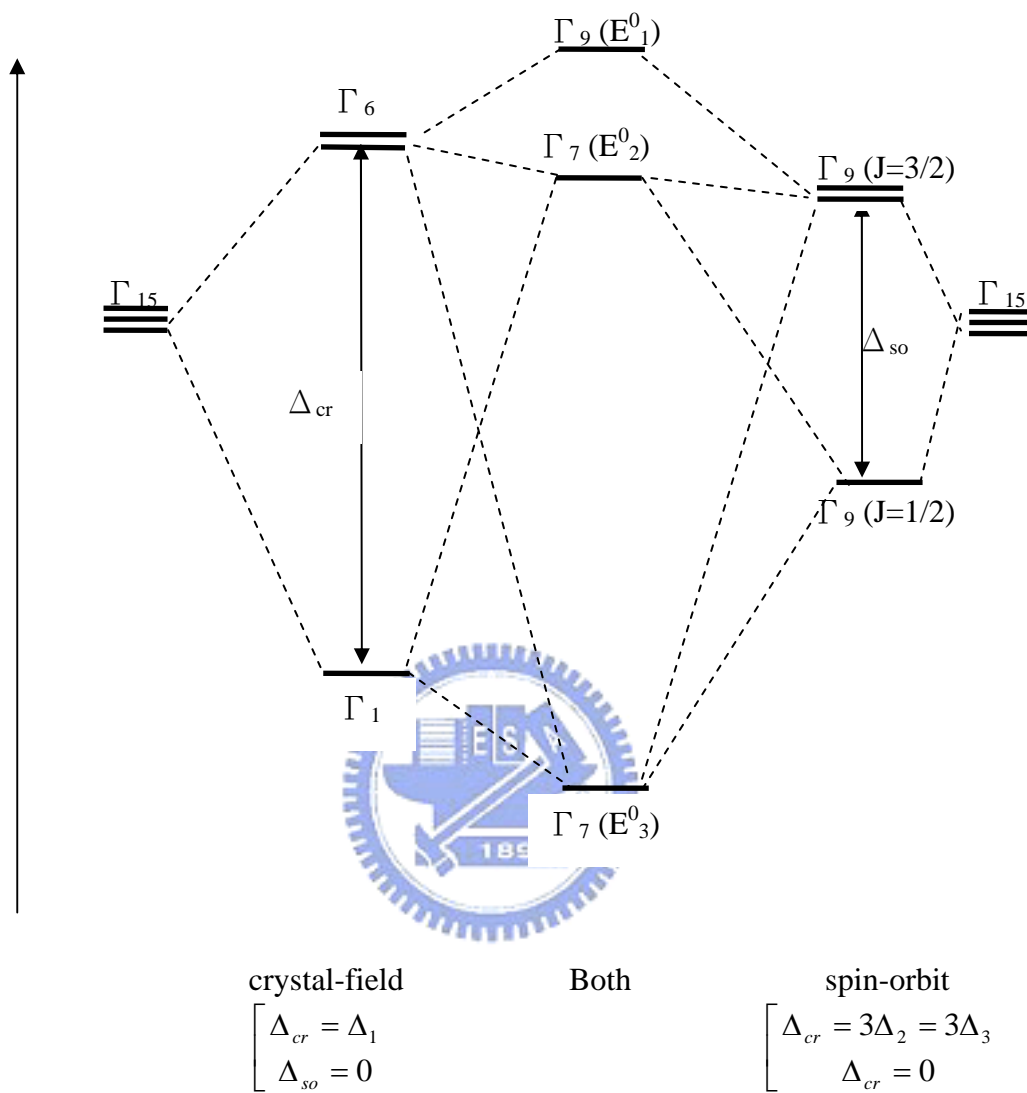


Figure 2-15. Energy splitting at the top of the valence bands of GaN under the influence of crystal-field and spin-orbit coupling. (The figure is not drawn to scale.)

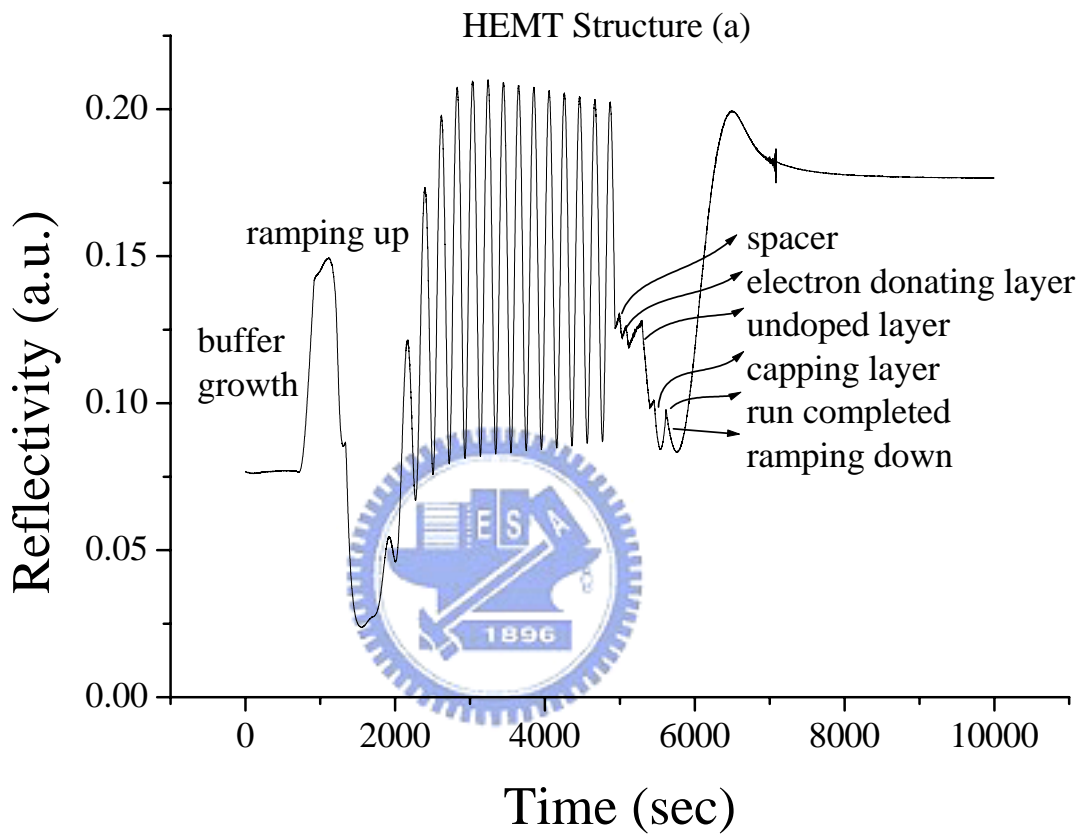


Figure 2-16. Typical reflection spectrum of U-GaN and AlGaIn/GaN HEMT.



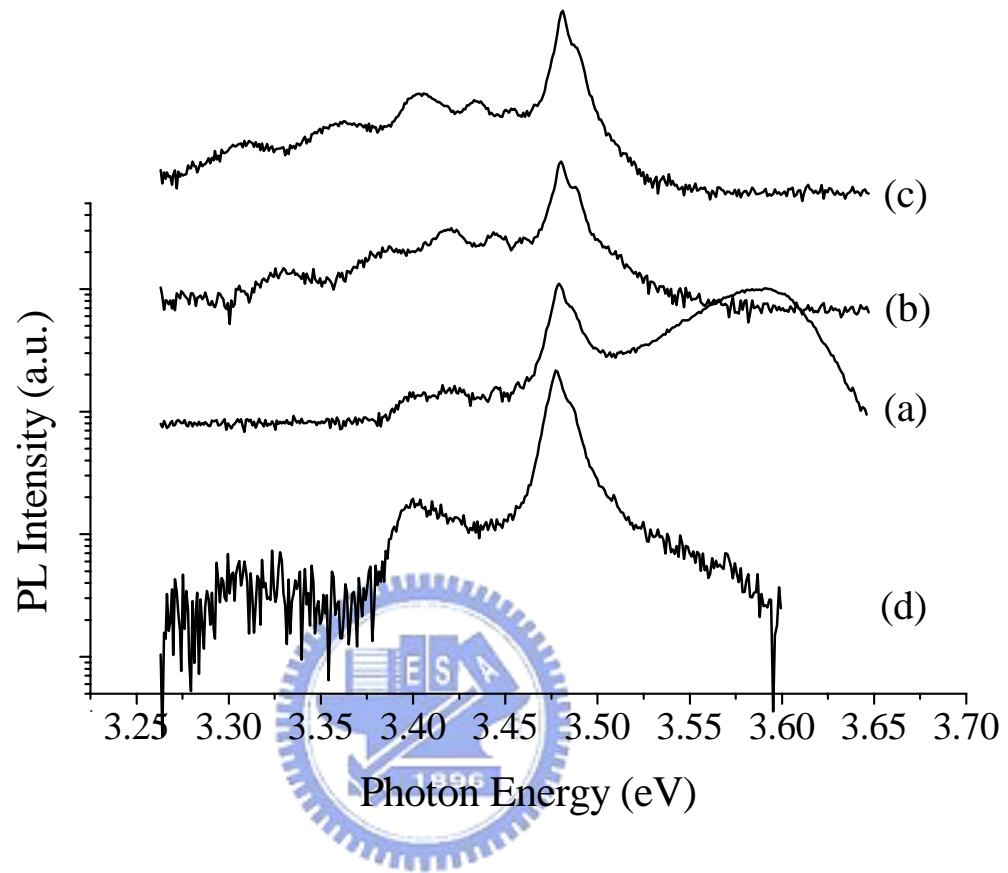


Figure 2-17. PL Spectra at 10 K for different structures of  $\text{Al}_{0.06}\text{Ga}_{0.94}\text{N} / \text{Al}_x\text{Ga}_{1-x}\text{N} / \delta$ -doping /  $\text{Al}_{0.15}\text{G}_{0.85}\text{N} / \text{GaN}$  HEMTs.

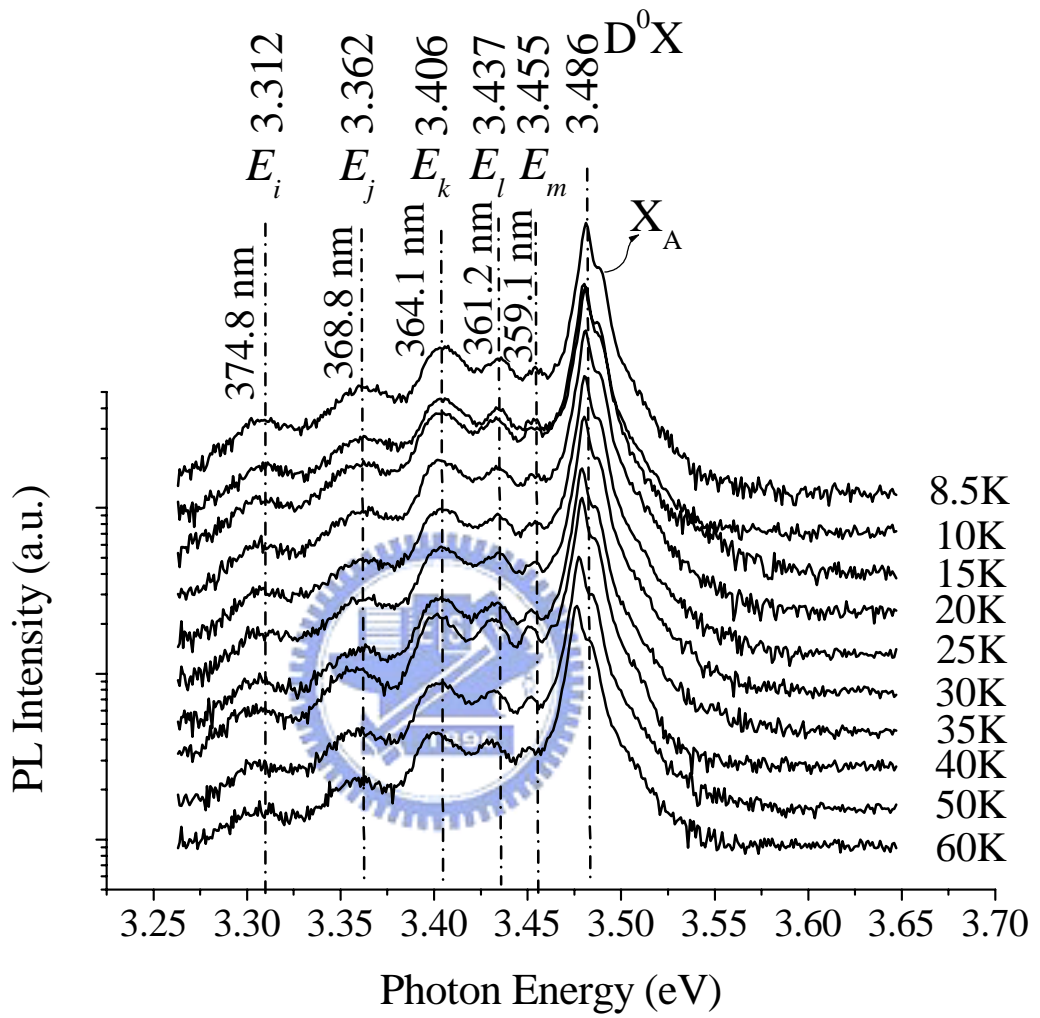


Figure 2-18. Temperature dependent PL spectra for the sample (c). Notice that the peak red-shift of the GaN  $D^0X$  is larger than that in 2-DEG.

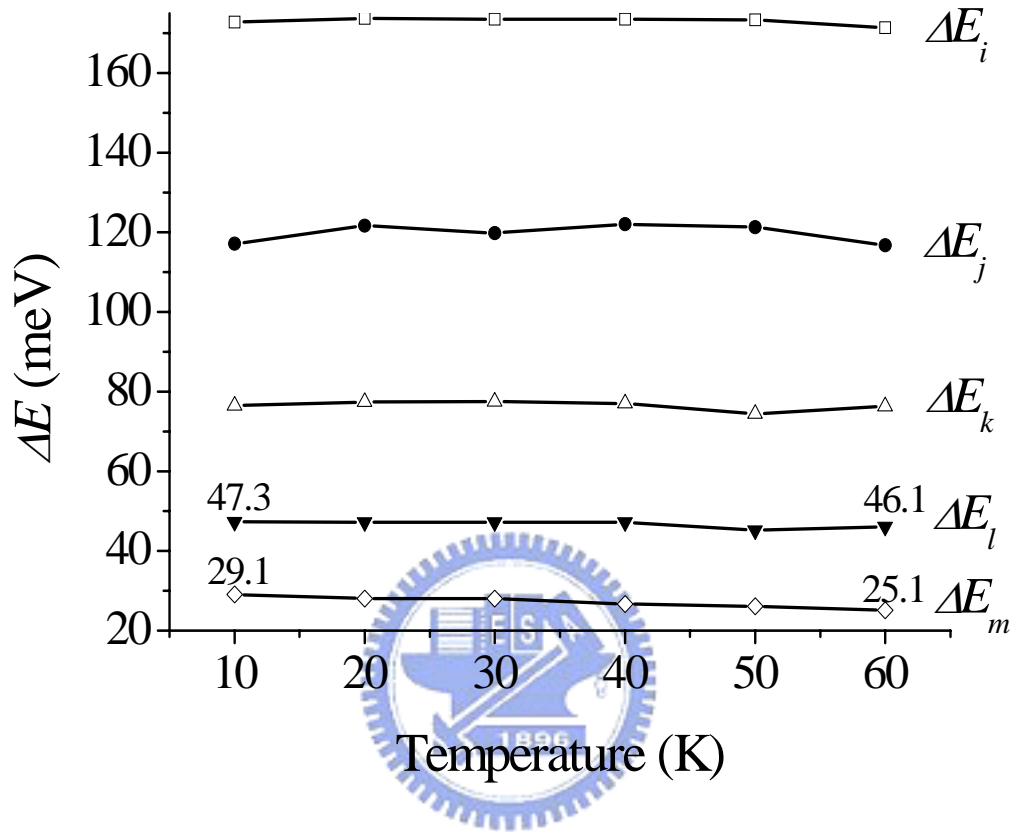
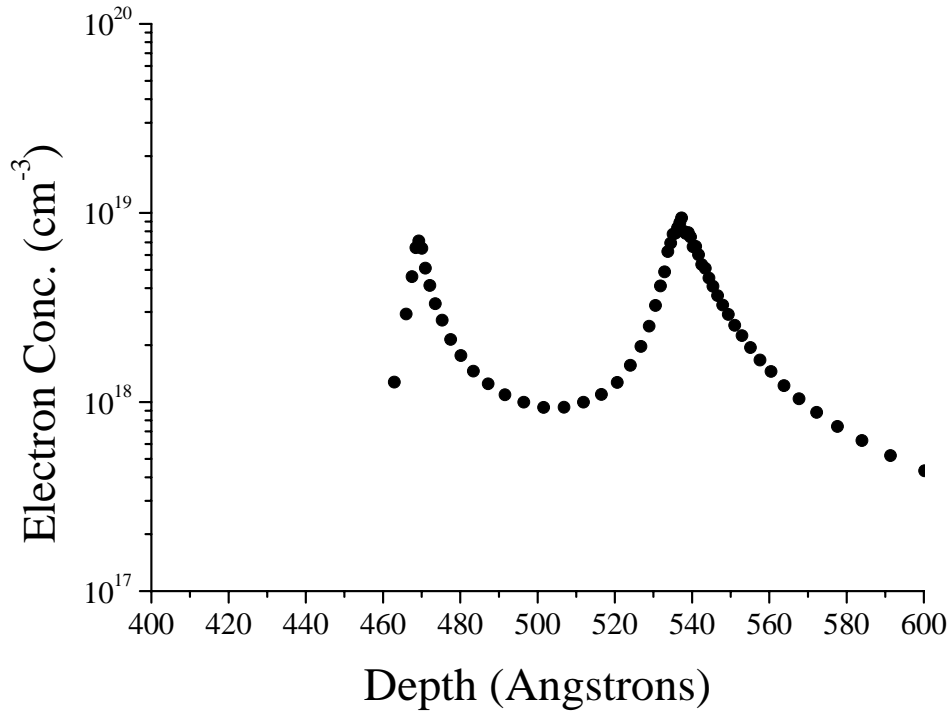
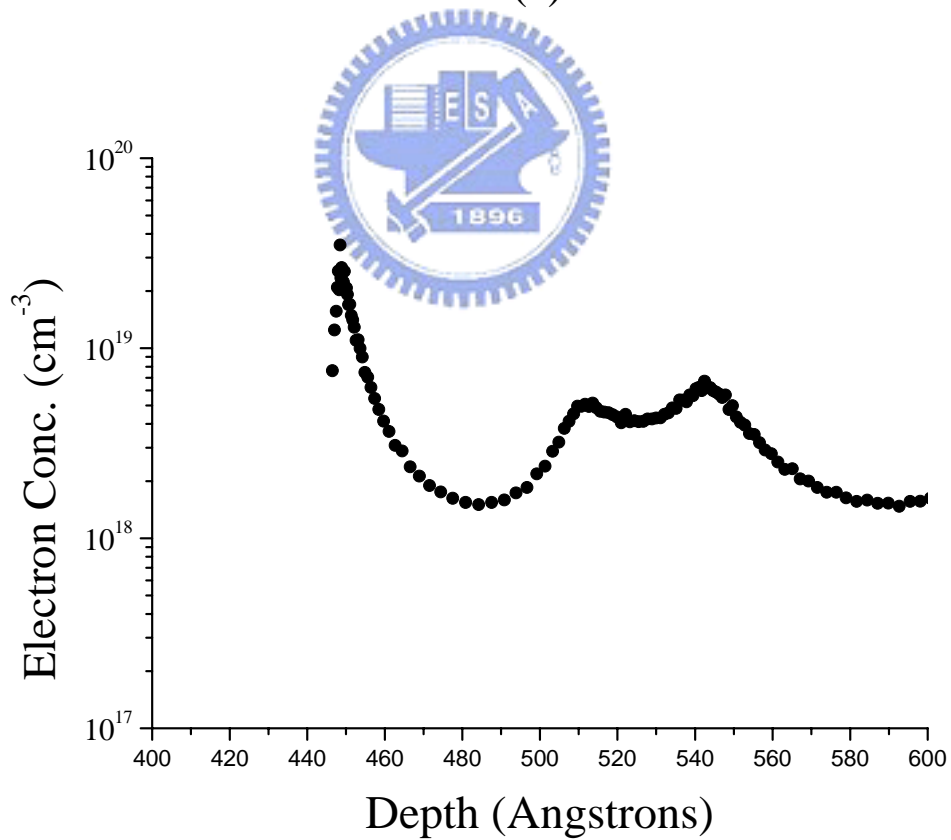


Figure 2-19. Temperature dependence of the energy separation ( $\Delta E$ ) of the 2DEG subbands PL peak from the GaN  $D^0X$  emission where  $\Delta E_i = E_{D^0X} - E_i$  and so on.



(a)



(b)

Figure 2-20. The CV plots of HEMT for (a) sample-c and (b) sample-d.